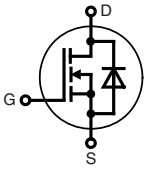
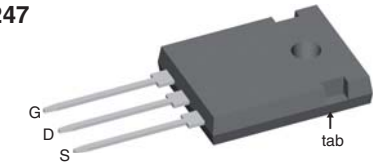
# CoolMOS™ 1) Power MOSFET

$V_{DSS}$ = 600 V
$I_{D25}$ = 47 A
$R_{DS(on)\ max}$ = 70 mΩ

Low $R_{DSon}$, high $V_{DSS}$
Superjunction MOSFET




TO-247




E72873

| MOSFET | | | | |
|---|---|---|---|---|
| **Symbol** | **Conditions** | | **Maximum Ratings** | |
| $V_{DSS}$ | $T_{VJ}$ = 25°C | | 600 | V |
| $V_{GS}$ | | | ± 20 | V |
| $I_{D25}$ | $T_C$ = 25°C | | 47 | A |
| $I_{D100}$ | $T_C$ = 100°C | | 30 | A |
| $E_{AS}$ | single pulse | $I_D$ = 10 A; $T_C$ = 25°C | 1800 | mJ |
| $E_{AR}$ | repetitive | $I_D$ = 20 A; $T_C$ = 25°C | tbd | mJ |
| dV/dt | MOSFET dV/dt ruggedness $V_{DS}$ = 0...480 V | | tbd | V/ns |

| **Symbol** | **Conditions** | **Characteristic Values** ($T_{VJ}$ = 25°C, unless otherwise specified) | | | |
|---|---|---|---|---|---|
| | | **min.** | **typ.** | **max.** | |
| $R_{DSon}$ | $V_{GS}$ = 10 V; $I_D$ = $I_{D100}$ ① | | 60 | 70 | mΩ |
| $V_{GS(th)}$ | $V_{DS}$ = $V_{GS}$; $I_D$ = 2 mA | 2 | | 4 | V |
| $I_{DSS}$ | $V_{DS}$ = $V_{DSS}$; $V_{GS}$ = 0 V; $T_{VJ}$ = 25°C | | | 25 | µA |
| | $T_{VJ}$ = 150°C | | | 250 | µA |
| $I_{GSS}$ | $V_{GS}$ = ± 20 V; $V_{DS}$ = 0 V | | | ±100 | nA |
| $C_{iss}$ | $V_{GS}$ = 0 V; $V_{DS}$ = 100 V | | tbd | | pF |
| $C_{oss}$ | f = 1 MHz | | tbd | | pF |
| $Q_g$ | $V_{GS}$ = 0 to 10 V; $V_{DS}$ = 350 V; $I_D$ = 40 A | | 255 | 650 | nC |
| $Q_{gs}$ | | | 30 | | nC |
| $Q_{gd}$ | | | 110 | | nC |
| $t_{d(on)}$ | $V_{GS}$ = 10 V; $V_{DS}$ = 380 V | | 20 | | ns |
| $t_r$ | $I_D$ = 47 A; $R_G$ = 4.7 Ω | | 27 | | ns |
| $t_{d(off)}$ | | | 111 | | ns |
| $t_f$ | | | 10 | | ns |
| $R_{thJC}$ | | | | 0.3 | K/W |

① Pulse test, t ≤ 300 µs, duty cycle d ≤ 2%

### Features

- 3rd generation Superjunction power MOSFET
  - high blocking capability
  - lowest resistance
  - avalanche rated for unclamped inductive switching (UIS)
  - low thermal resistance due to reduced chip thickness

### Applications

- Switched mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)
- Power factor correction (PFC)
- Welding
- Inductive heating

1) CoolMOS™ is a trademark of Infineon Technologies AG.

## Source-Drain Diode

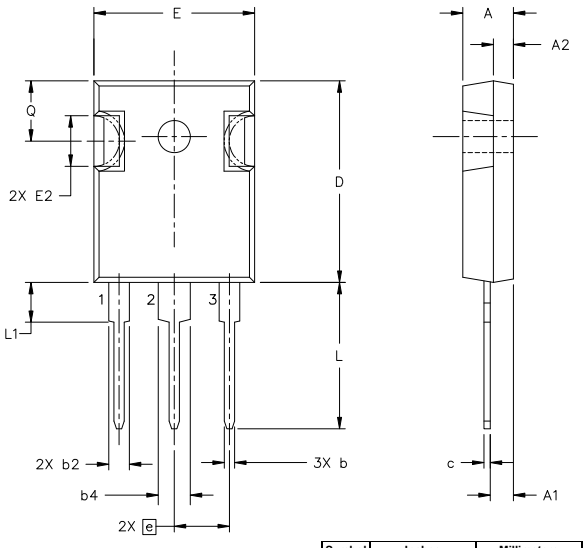
| Symbol | Conditions | Characteristic Values ($T_{VJ}$ = 25°C, unless otherwise specified) min. | typ. | max. | |
|---|---|---|---|---|---|
| $I_S$ | $V_{GS}$ = 0 V | | | | A |
| $V_{SD}$ | $I_F$ = 40 A; $V_{GS}$ = 0 V | | | | V |
| $t_{rr}$ | $I_F$ = 40 A; -$di_F$/dt = 100 A/µs; $V_R$ = 640 V | | | | ns |
| $Q_{RM}$ | | | | | µC |
| $I_{RM}$ | | | | | A |

## Component

| Symbol | Conditions | Maximum Ratings | |
|---|---|---|---|
| $T_{VJ}$ | operating | -55...+150 | °C |
| $T_{stg}$ | | -55...+150 | °C |
| $M_d$ | mounting torque | 1.13 | Nm |

| Symbol | Conditions | Characteristic Values min. | typ. | max. | |
|---|---|---|---|---|---|
| $R_{thCH}$ | with heatsink compound | | tbd | | K/W |
| Weight | | | 2.7 | | g |

### TO-247 Outline




| Symbol | Inches min | Inches max | Millimeters min | Millimeters max |
|---|---|---|---|---|
| A | 0.185 | 0.209 | 4.70 | 5.30 |
| A1 | 0.087 | 0.102 | 2.21 | 2.59 |
| A2 | 0.059 | 0.098 | 1.50 | 2.49 |
| D | 0.819 | 0.845 | 20.79 | 21.45 |
| E | 0.610 | 0.640 | 15.48 | 16.24 |
| E2 | 0.170 | 0.216 | 4.31 | 5.48 |
| e | 0.215 BSC | | 5.46 BSC | |
| L | 0.780 | 0.800 | 19.80 | 20.30 |
| L1 | - | 0.177 | - | 4.49 |
| ØP | 0.140 | 0.144 | 3.55 | 3.65 |
| Q | 0.212 | 0.244 | 5.38 | 6.19 |
| S | 0.242 BSC | | 6.14 BSC | |
| b | 0.039 | 0.055 | 0.99 | 1.40 |
| b2 | 0.065 | 0.094 | 1.65 | 2.39 |
| b4 | 0.102 | 0.135 | 2.59 | 3.43 |
| c | 0.015 | 0.035 | 0.38 | 0.89 |
| D1 | 0.515 | - | 13.07 | - |
| D2 | 0.020 | 0.053 | 0.51 | 1.35 |
| E1 | 0.530 | - | 13.45 | - |
| ØP1 | - | 0.291 | - | 7.39 |

**Fig. 1. Output Characteristics @ 25 Deg. C**

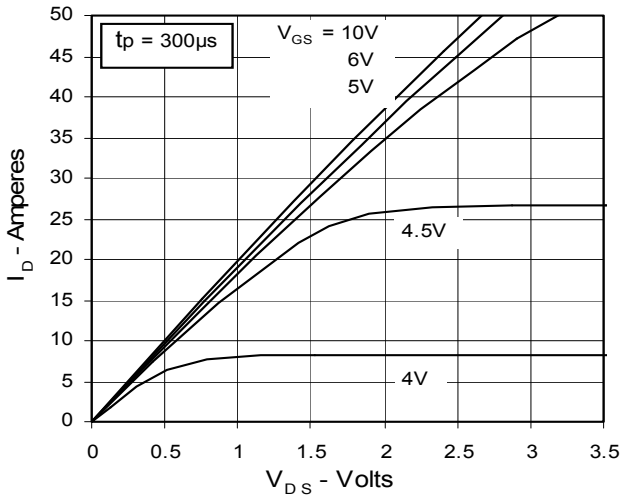



**Fig. 2. Extended Output Characteristics @ 25 deg. C**

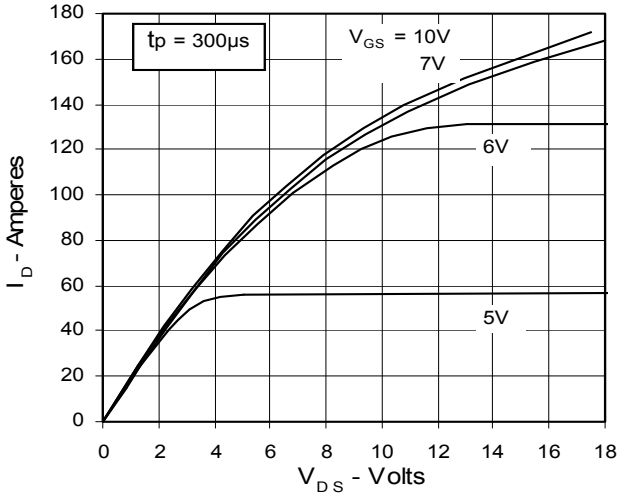



**Fig. 3. Output Characteristics @ 125 Deg. C**

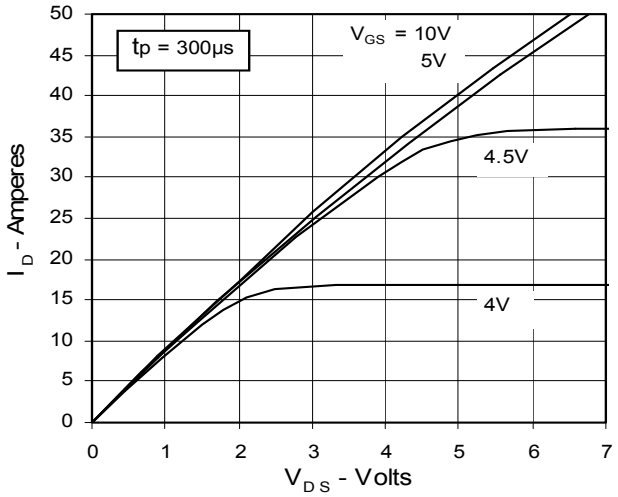



**Fig. 4. $R_{DS(on)}$ Normalized to $I_{D100}$ Value vs. Junction Temperature**

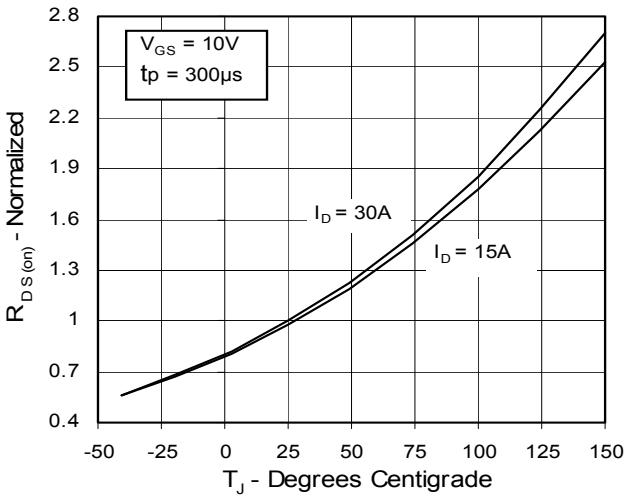



**Fig. 5. $R_{DS(on)}$ Normalized to $I_{D100}$ Value vs. $I_D$**

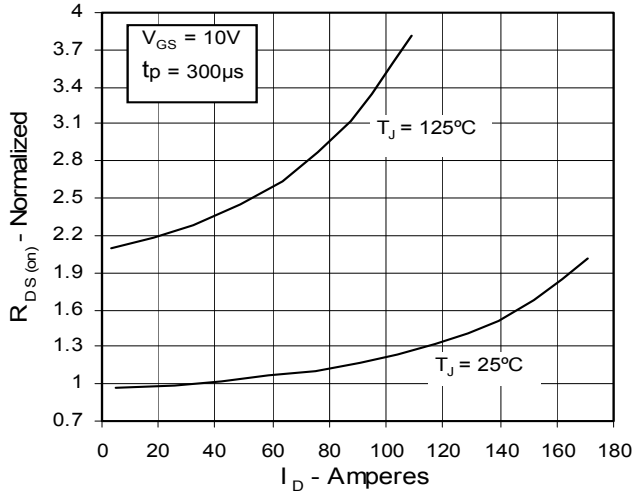



**Fig. 6. Drain Current vs. Case Temperature**

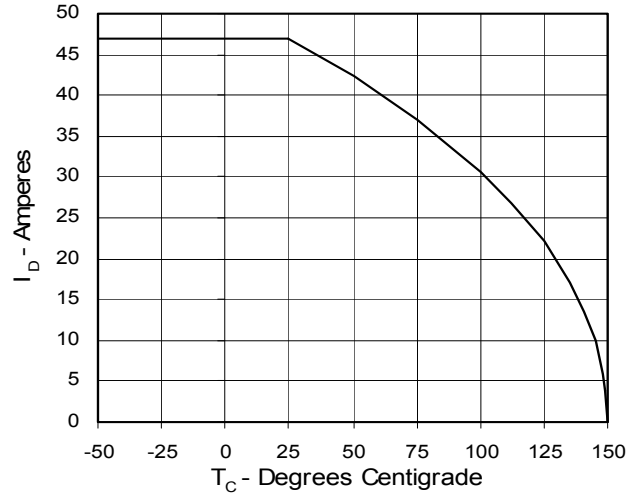


**Fig. 7. Input Admittance**

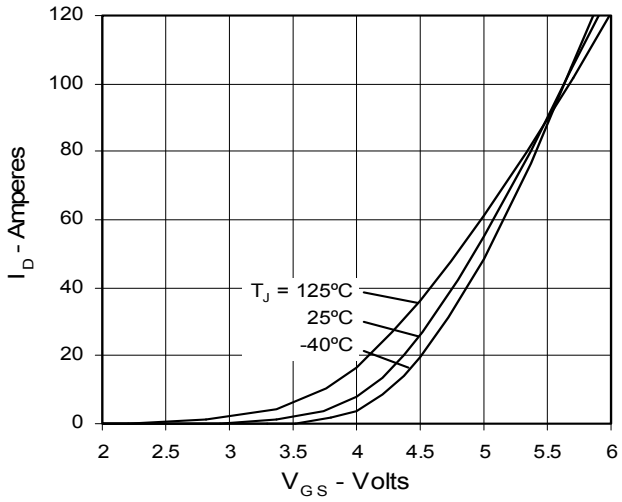



**Fig. 8. Transconductance**

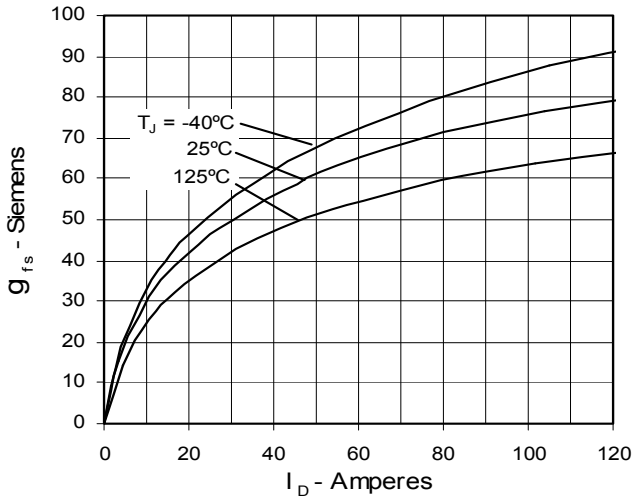



**Fig. 9. Source Current vs. Source-To-Drain Voltage**

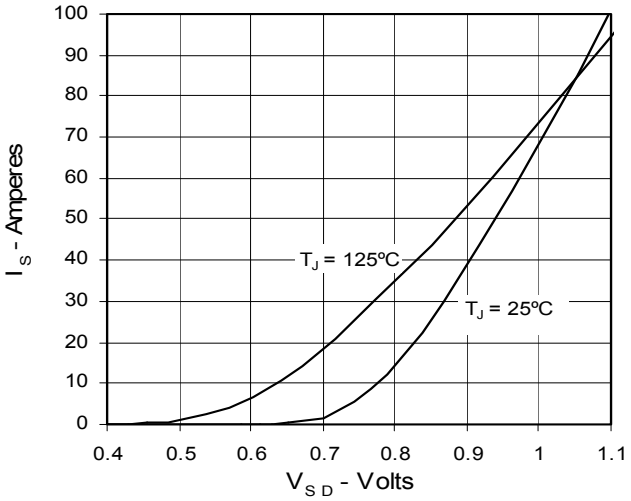



**Fig. 10. Gate Charge**

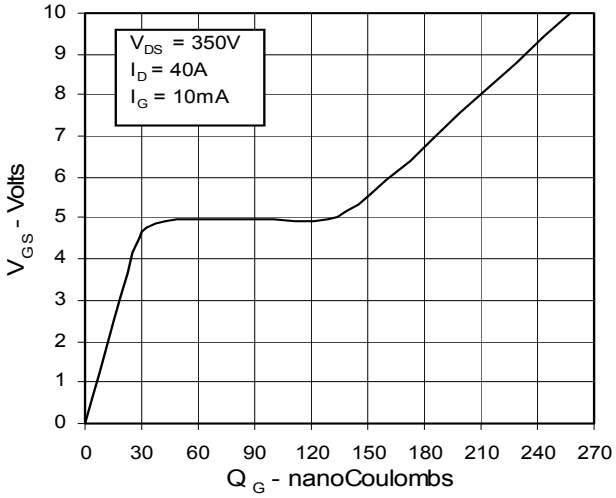



**Fig. 11. Capacitance**

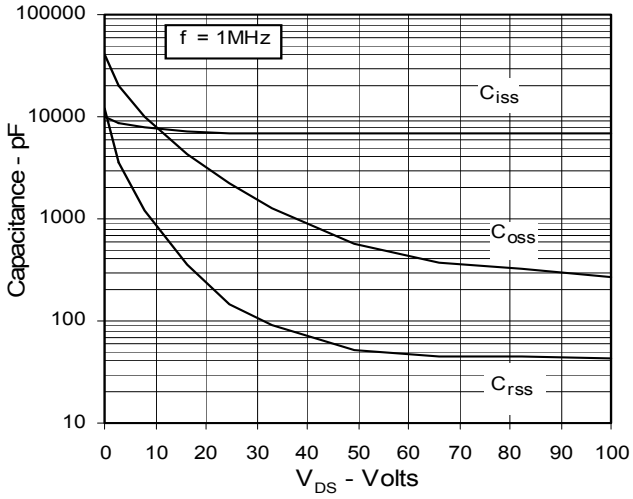
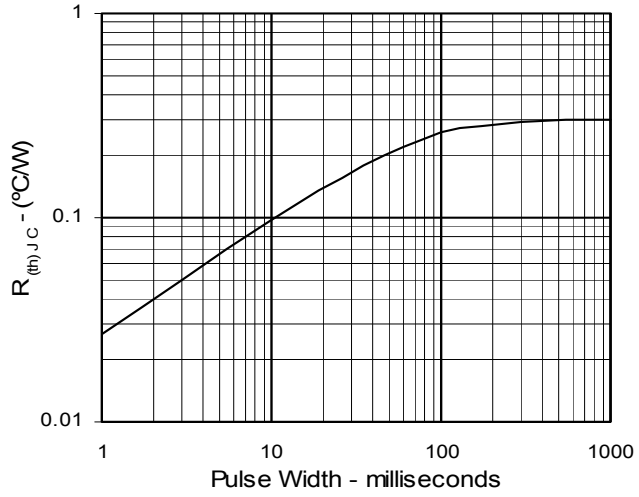



**Fig. 12. Maximum Transient Thermal Resistance**



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